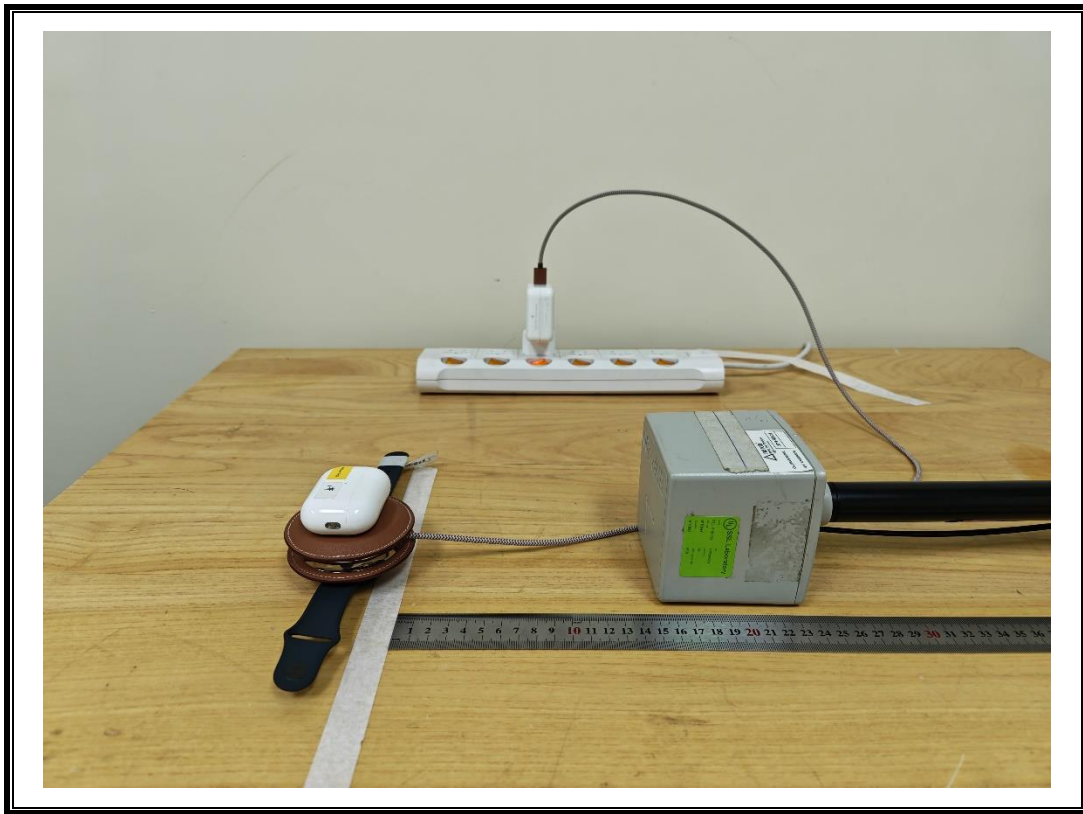


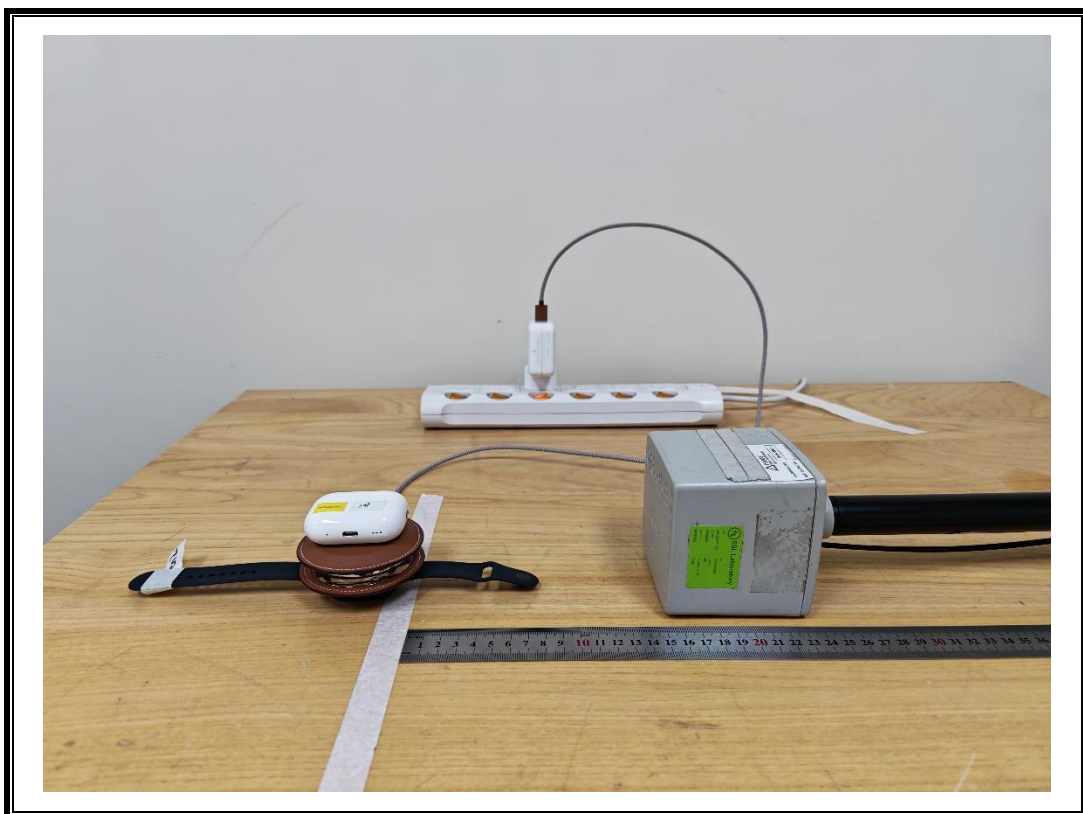
Appendix III -1

Setup Photographs

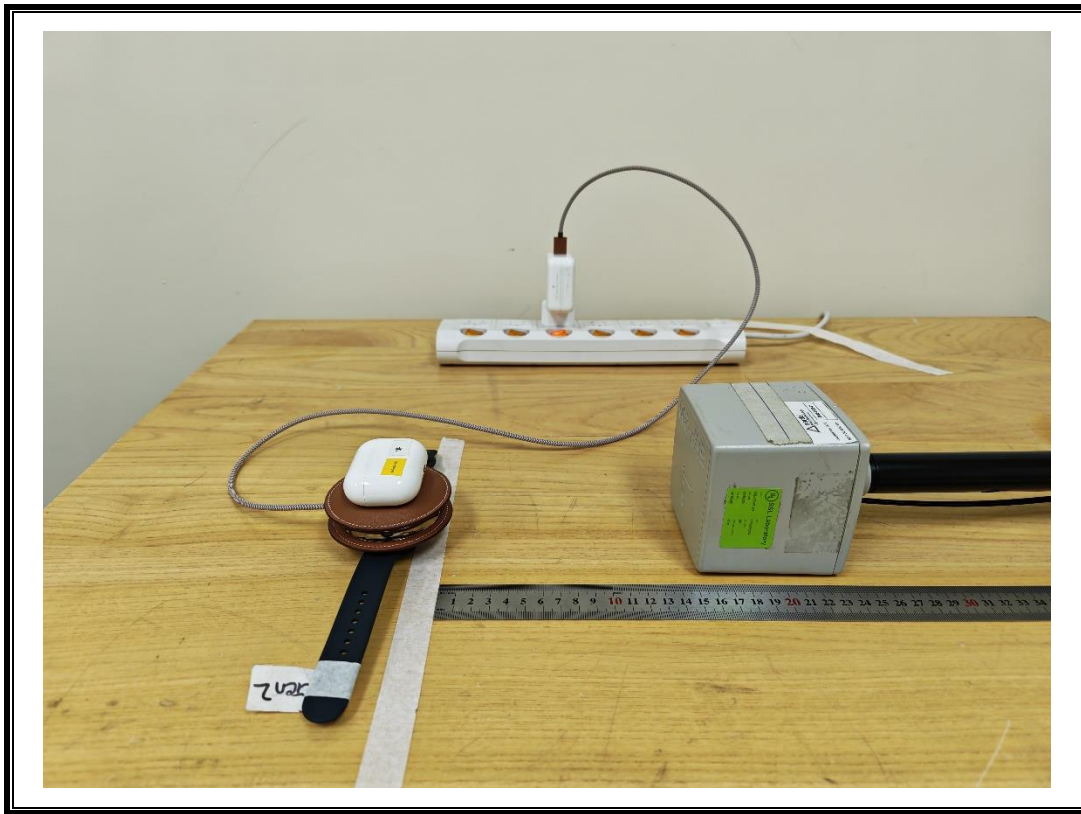
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-1



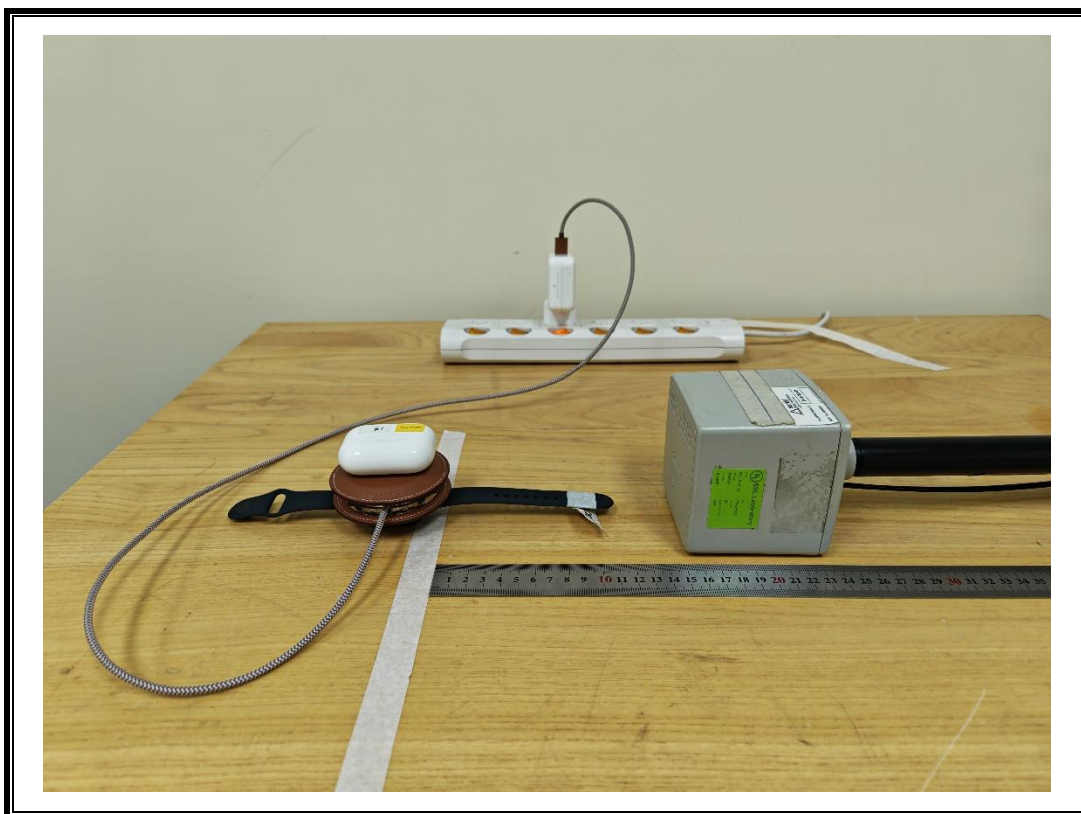
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-2



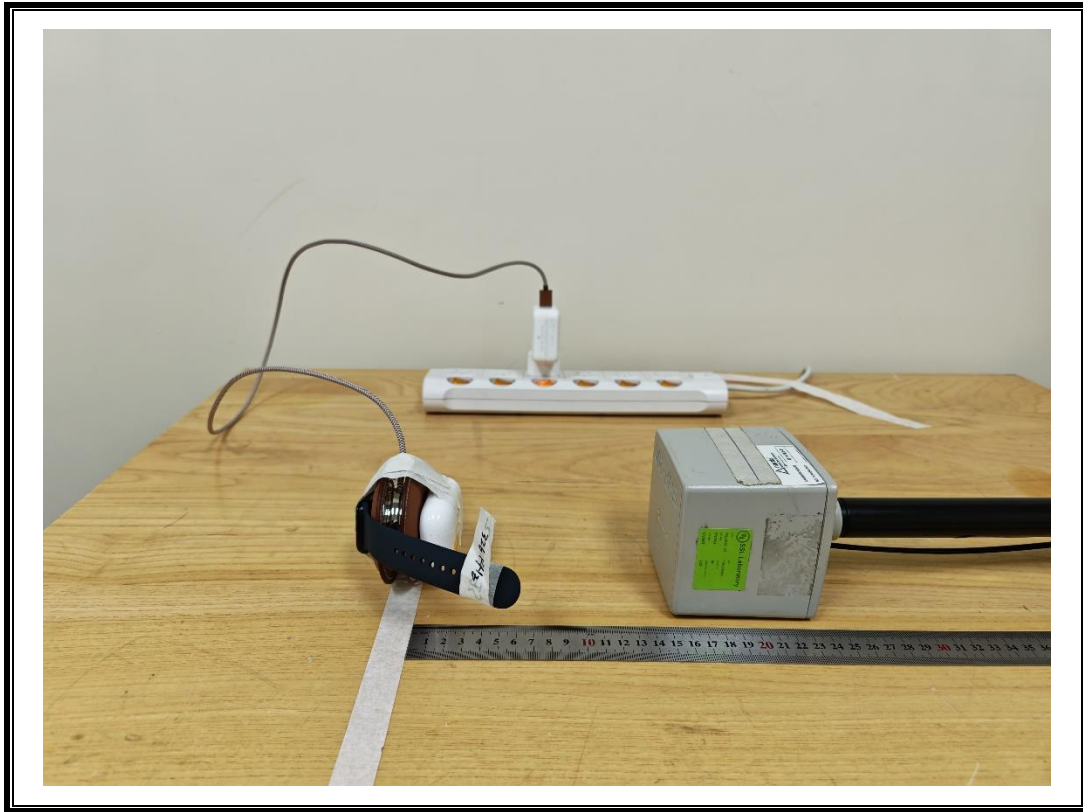
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-3



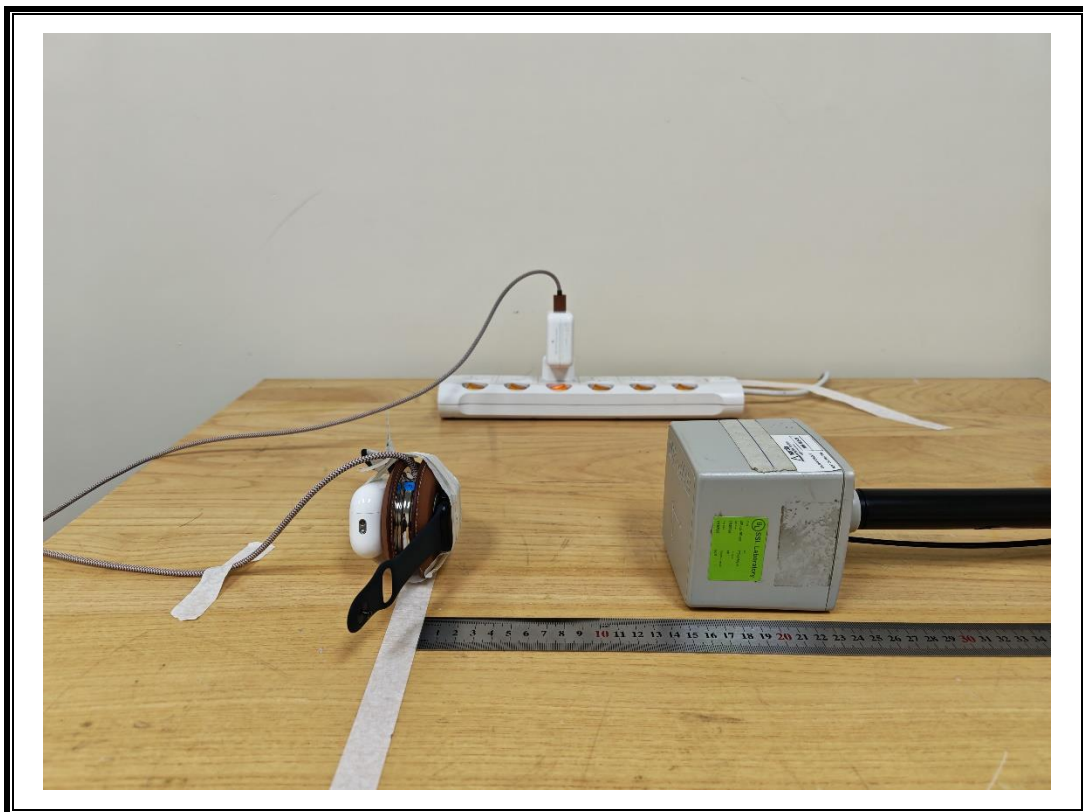
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-4



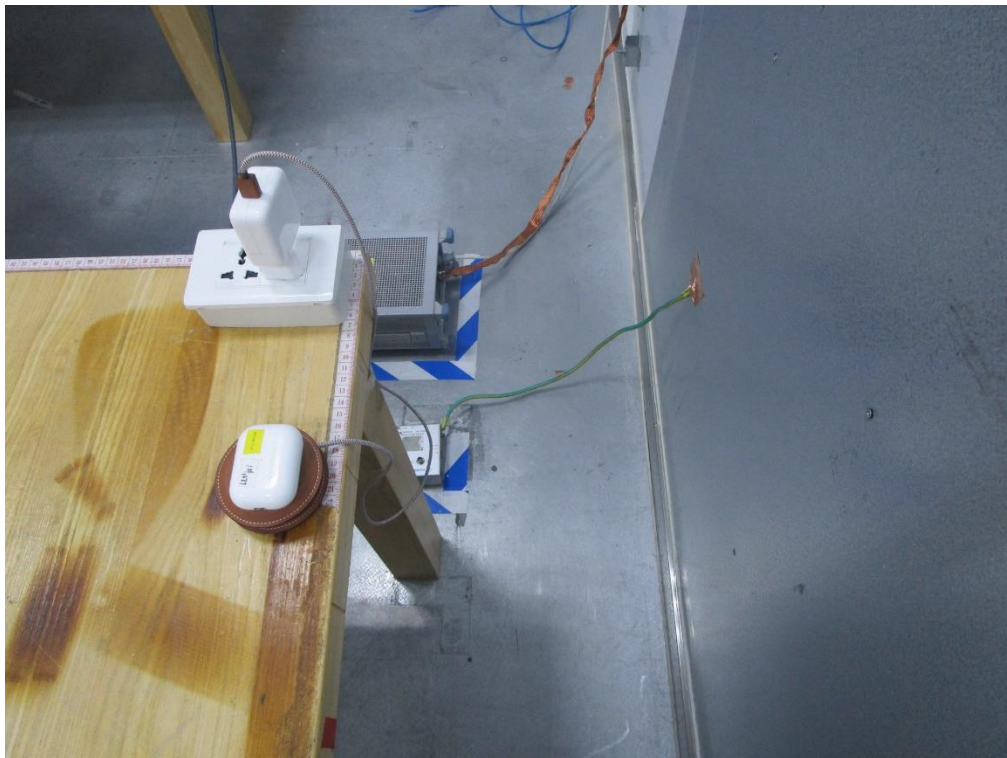
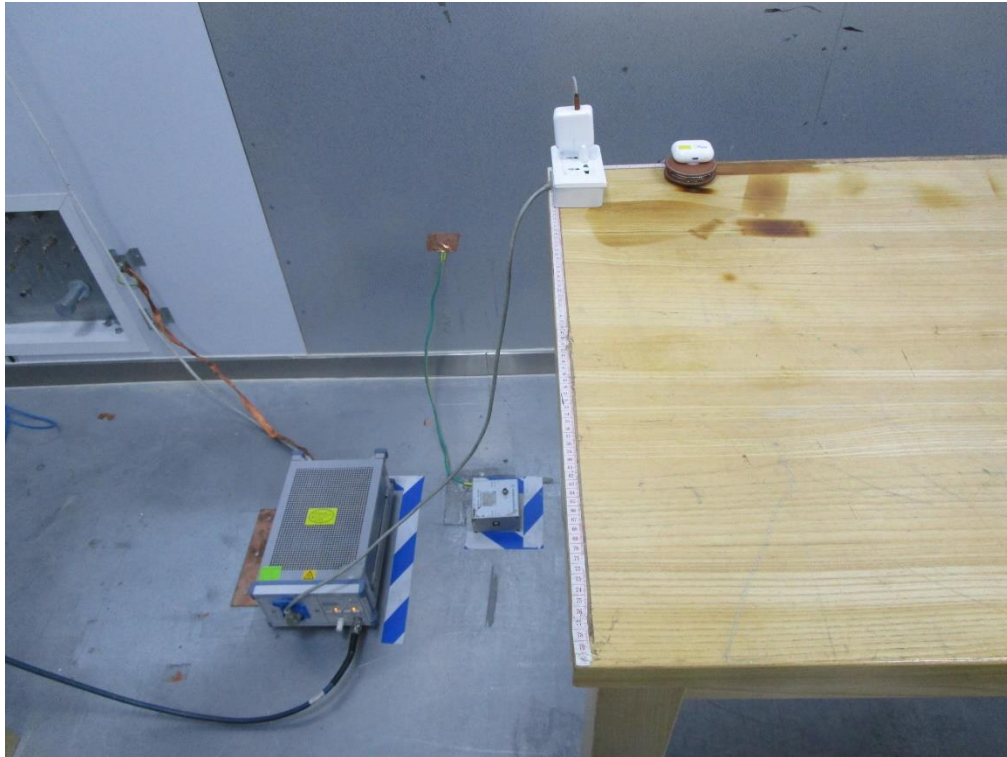
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP



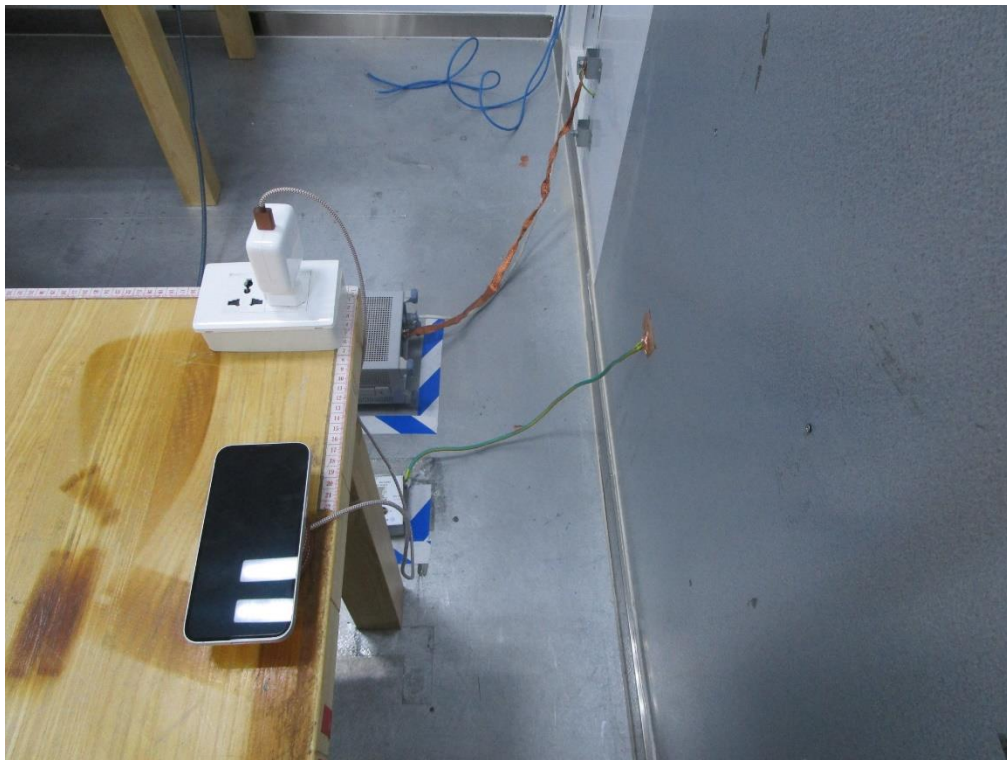
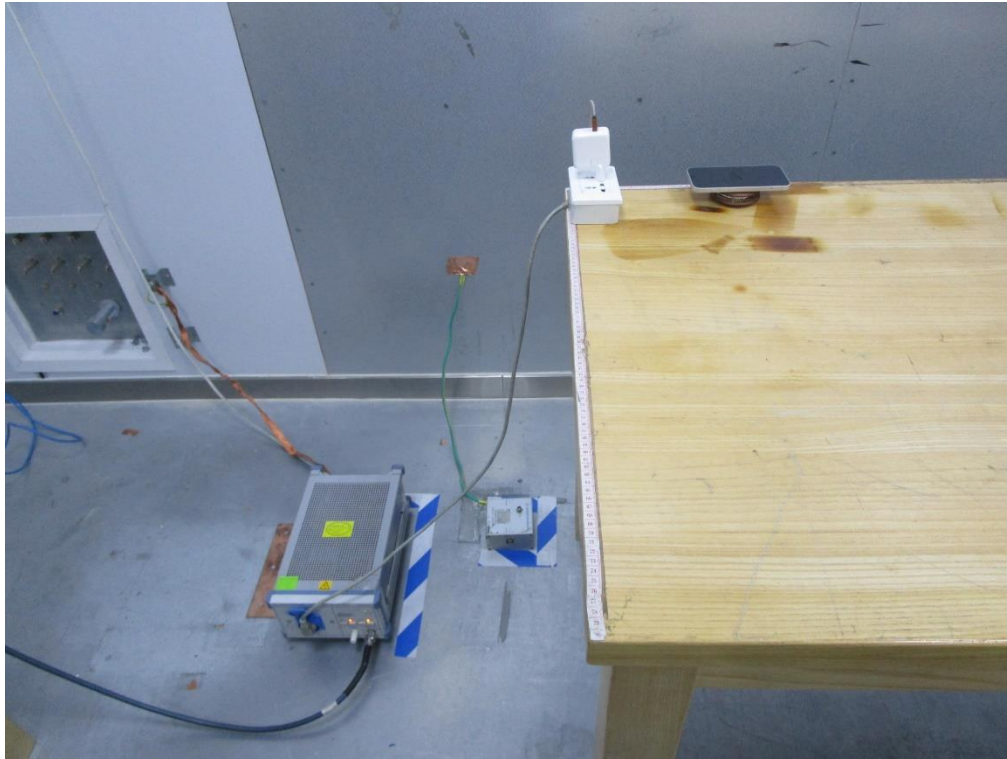
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-6



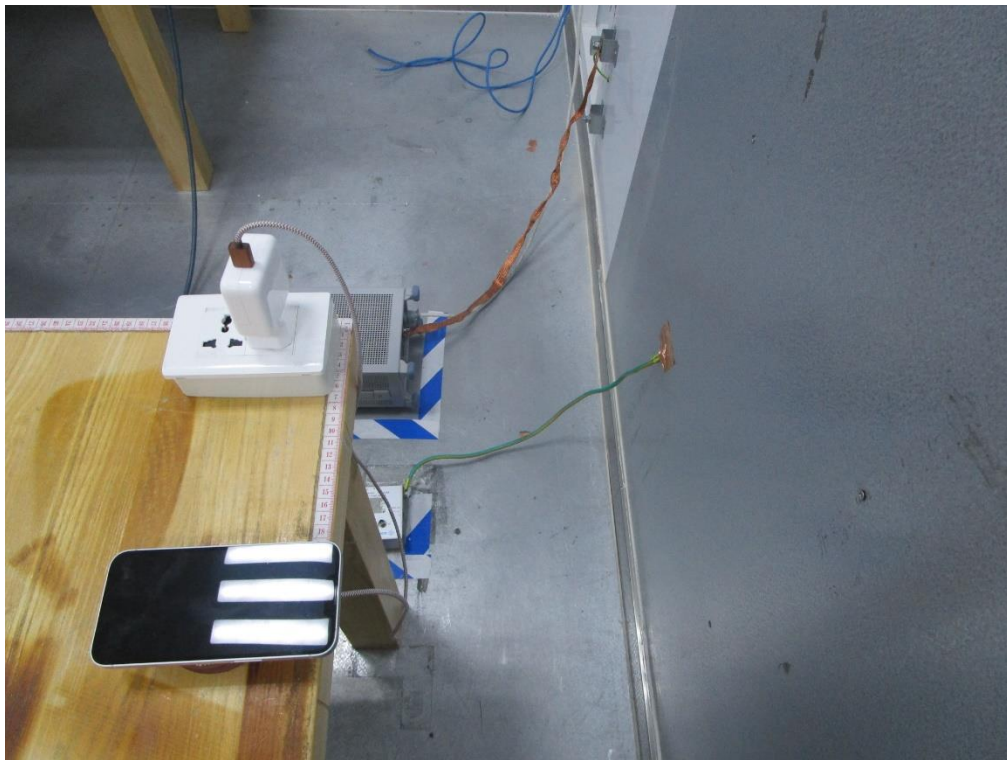
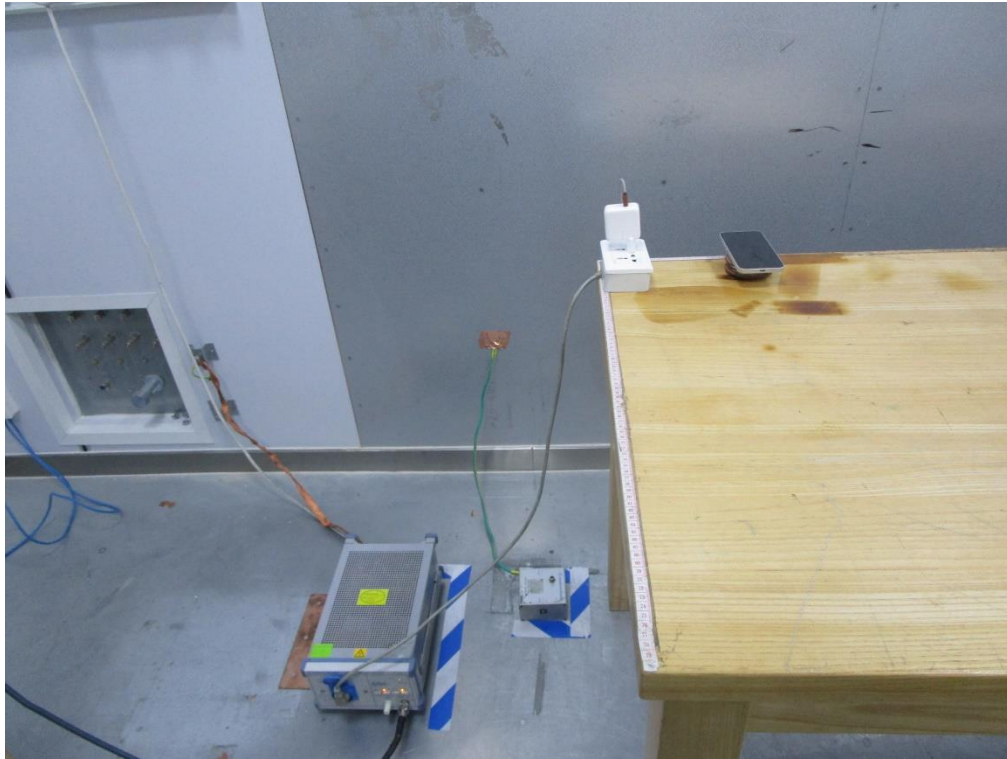
Conducted emissions
M01



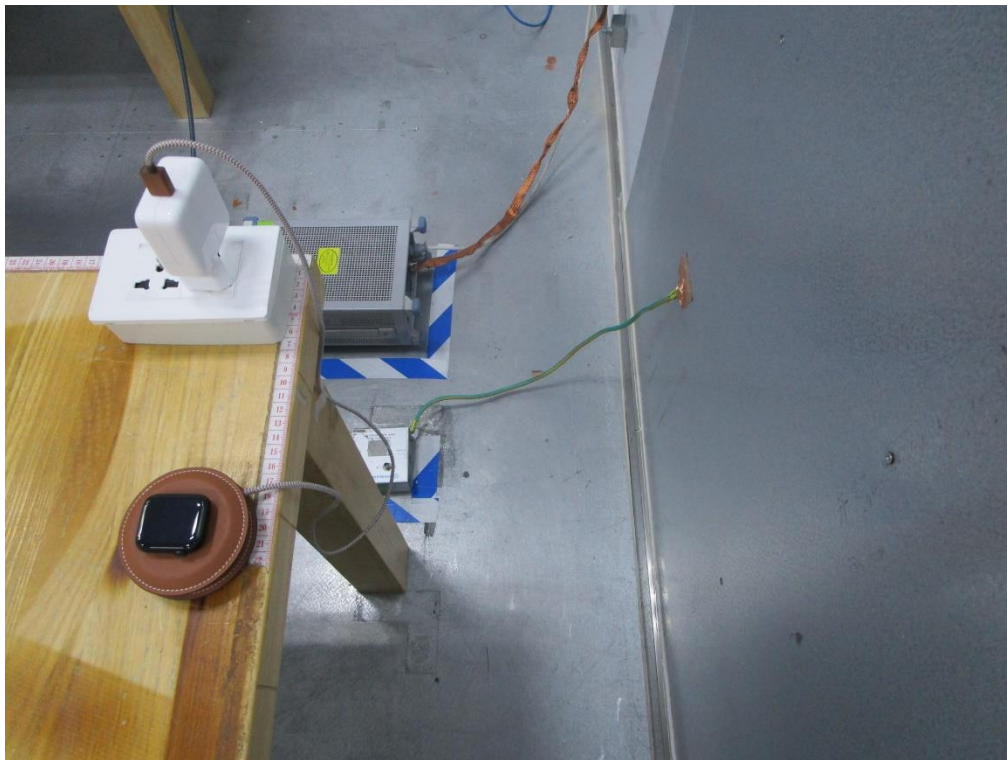
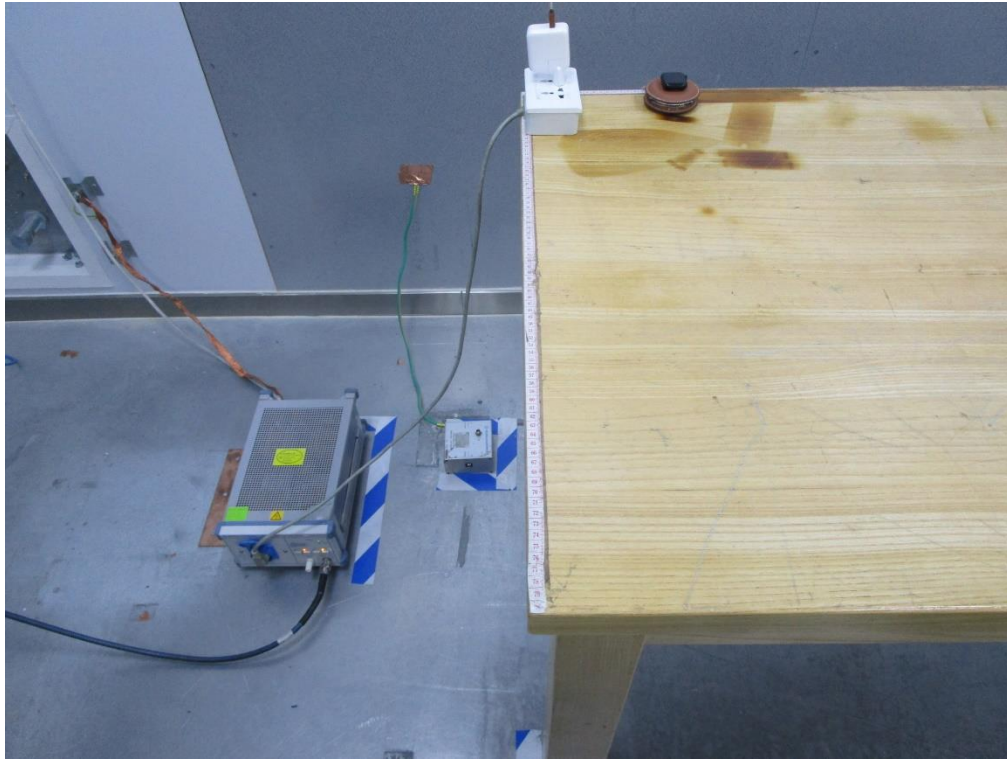
M02



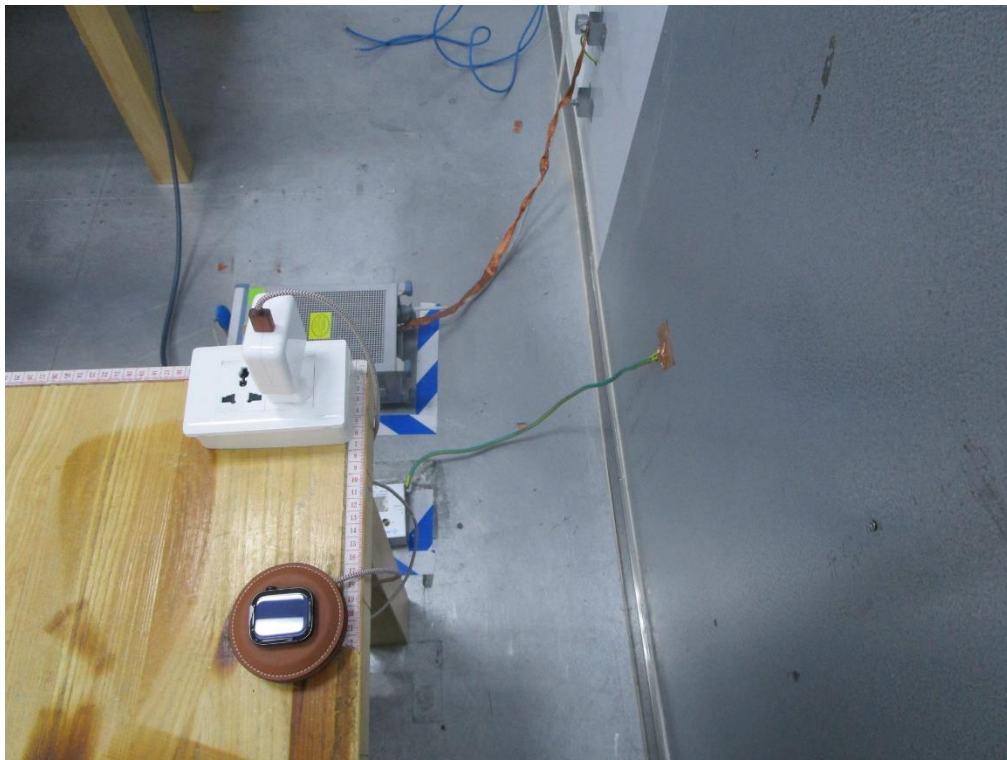
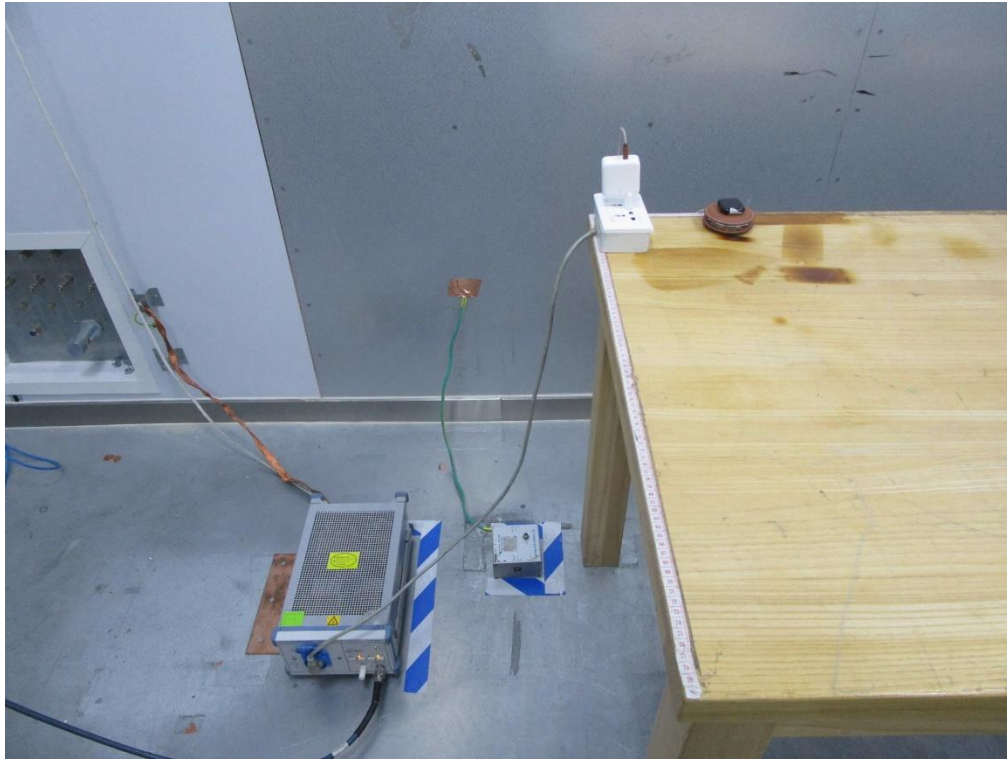
M03



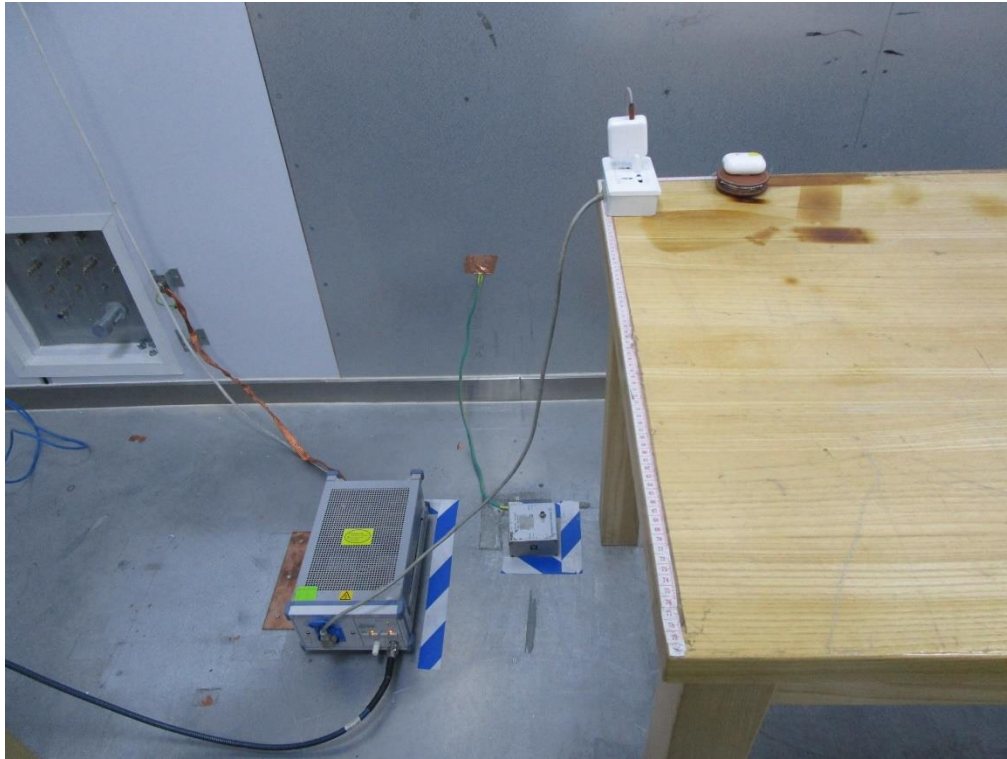
M04



M05



M06

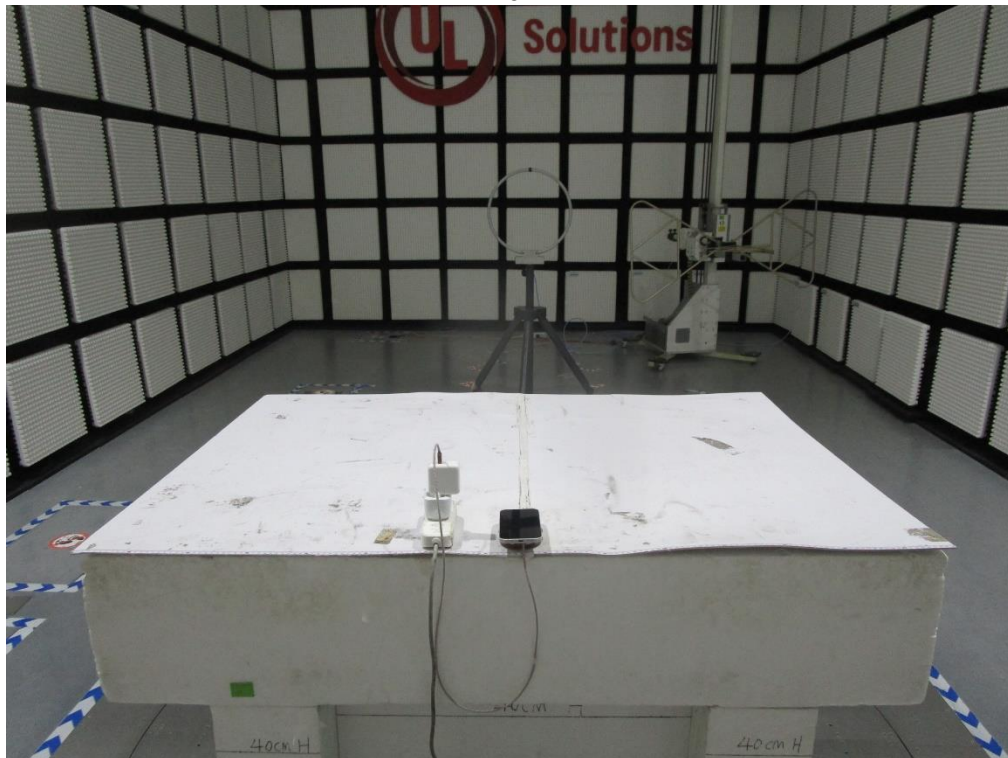


Radiated emissions below 30MHz

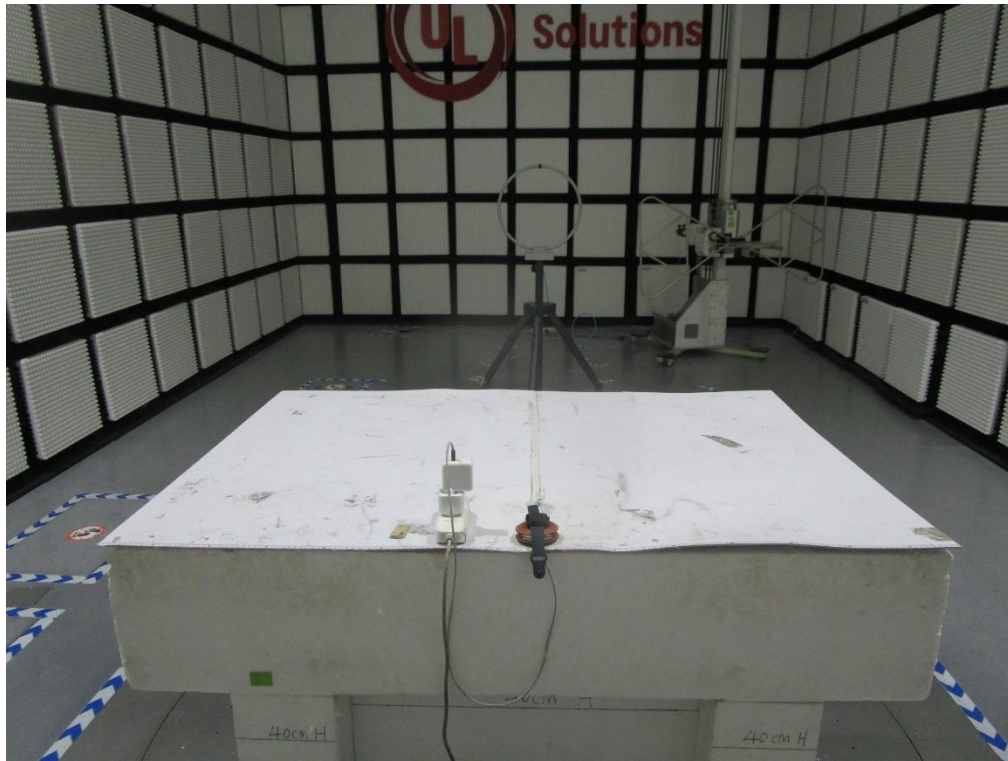
M01



M02



M05



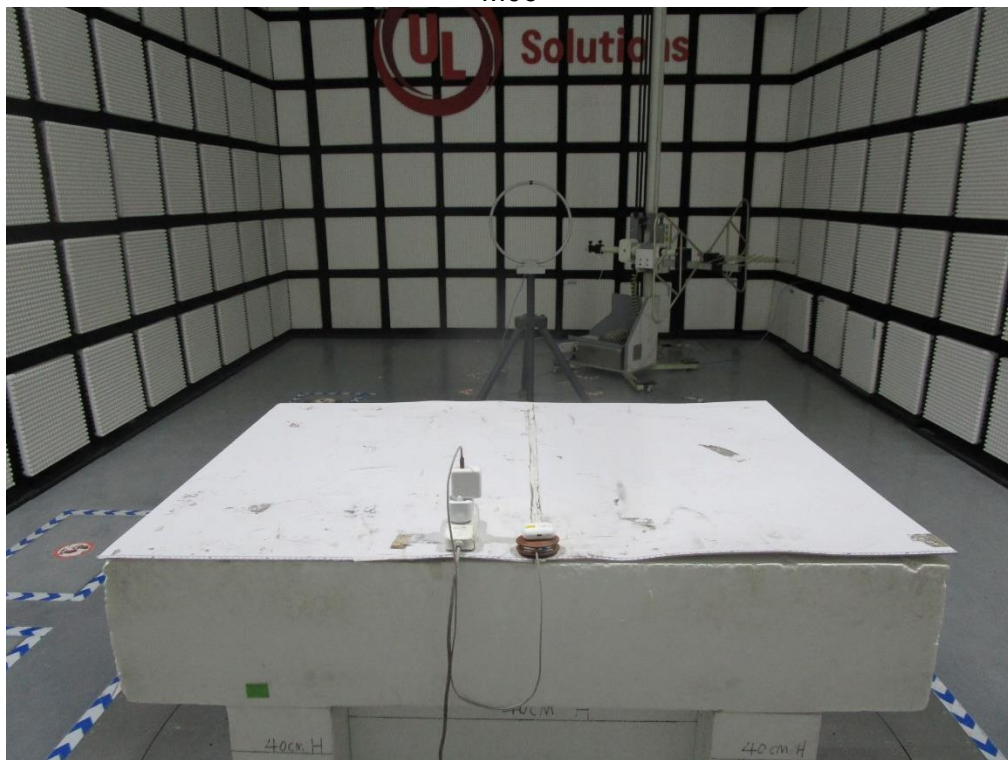
M04



M03



M06



Radiated emissions below 1GHz

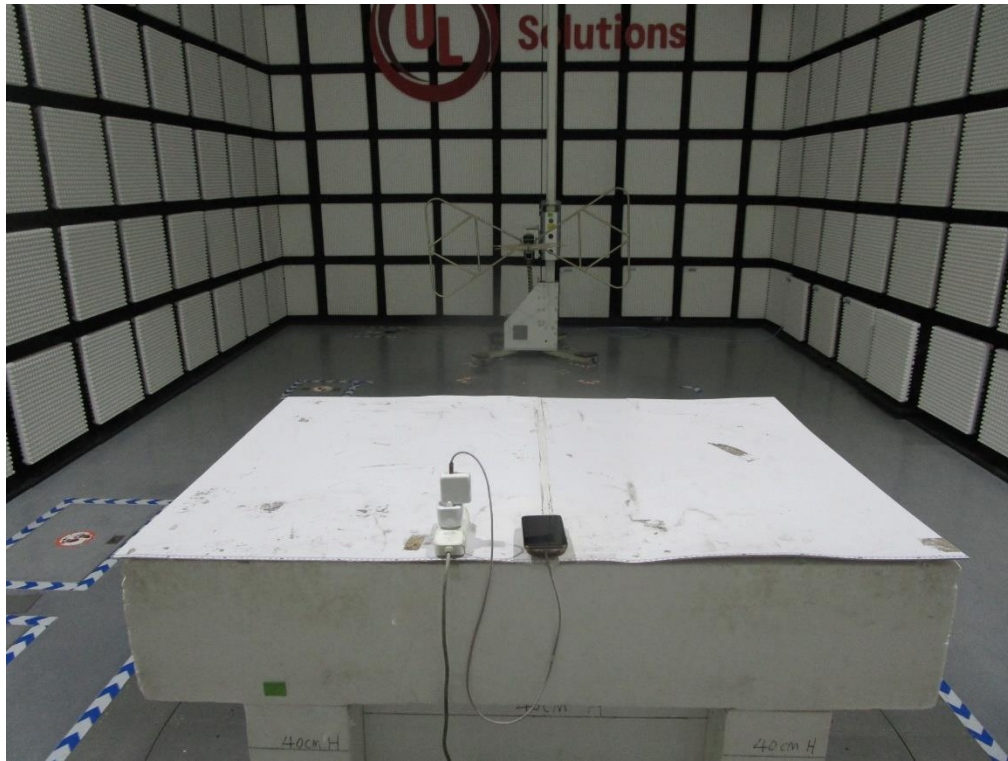
M01



M02



M03



M04



M05



M06

